

Amendment t the Abstract:

The Abstract has been amended. A revised Abstract is attached.

ABSTRACT

~~A component mounter for picking up a component and mounting it on a board using a transfer head. A position of solder paste printed on an electrode on a board is previously measured and a measurement result is stored. Mounting coordinates for mounting the component using the transfer head is calculated based on this measurement result. In the mounting operation, the transfer head is controlled using mounting coordinates determined based on the solder printing position so as to mount the component on each electrode on the board. This prevents the occurrence of positional deviation between the mounted component and printed solder paste. Defective mounting, which may occur in a reflow process due to positional deviation, is thus preventable.~~ A method of mounting a component on an electrode on a board. Mounting coordinates for mounting the component are calculated. A determination is made of printing positions where solder for the component is situation on the electrode. The printing positions of the solder are stored. Mounting position data for where the component is to be mounted on the solder is prepared based on the previous steps. The component is mounted using the information gathered in the previous steps.

Respectfully submitted,


Lawrence E. Ashery, Reg. No. 34,515
Attorney for Applicants

LEA/fp

Attachment: Abstract

Dated: October 29, 2003

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ABSTRACT

A method of mounting a component on an electrode on a board. Mounting coordinates for mounting the component are calculated. A determination is made of printing positions where solder for the component is situation on the electrode. The printing positions of the solder are stored. Mounting position data for where the component is to be mounted on the solder is prepared based on the previous steps. The component is mounted using the information gathered in the previous steps.